SCAS109F - APRIL 1990 - REVISED OCTOBER 1998

- Low-Skew Propagation Delay Specifications for Clock-Driver Applications
- TTL-Compatible Inputs and CMOS-Compatible Outputs
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V<sub>CC</sub> and GND Pin Configurations Minimize High-Speed Switching Noise
- EPIC ™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (DW)

#### (TOP VIEW) 20 1Y1 1Y2 1Y3 1 2 19 | 1A 18 10E1 1Y4 🛮 3 GND 4 17 10E2 16 V<sub>CC</sub> GND 5 GND 6 15 VCC GND ∏ 7 14 2A 2Y1 **8** 13 2OE1 2Y2 🛮 9 12 2OE2 2Y3 🛮 10 11 2Y4

**DW PACKAGE** 

## description

The CDC208 contains dual clock-driver circuits that fanout one input signal to four outputs with minimum skew for clock distribution (see Figure 2). The device also offers two output-enable (OE1 and OE2) inputs for each circuit that can force the outputs to be disabled to a high-impedance state or to a high- or low-logic level independent of the signal on the respective A input.

Skew parameters are specified for a reduced temperature and voltage range common to many applications.

The CDC208 is characterized for operation from -40°C to 85°C.

**FUNCTION TABLES** 

	INPUTS			OUTI	PUTS	
1 <del>0E</del> 1	10E2	1A	1Y1	1Y2	1Y3	1Y4
L	L	L	L	L	L	L
L	L	Н	Н	Н	Н	Н
L	Н	Χ	L	L	L	L
Н	L	Χ	Н	Н	Н	Н
Н	Н	Χ	Z	Z	Z	Z

	INPUTS		OUTPUTS					
2OE1	2OE2	2A	2Y1	2Y2	2Y3	2Y4		
L	L	L	L	L	L	L		
L	L	Н	Н	Н	Н	Н		
L	Н	Χ	L	L	L	L		
Н	L	Χ	Н	Н	Н	Н		
Н	Н	Χ	Z	Z	Z	Z		

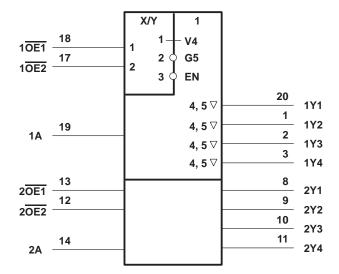


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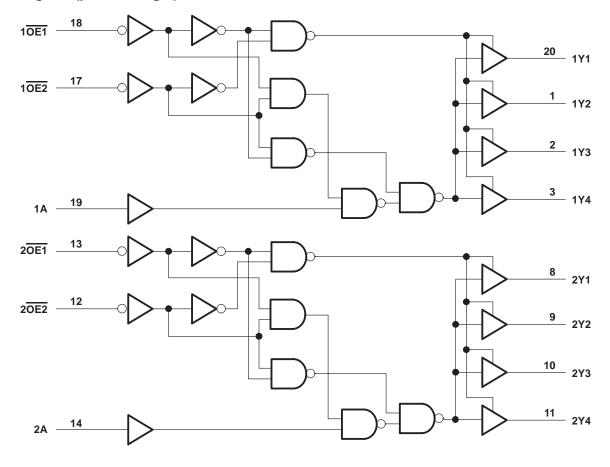


## logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)





# DUAL 1-LINE TO 4-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V <sub>O</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
Continuous output current, I <sub>O</sub> (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±200 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	1.6 W
Storage temperature range	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
 For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

## recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			V
$V_{IL}$	Low-level input voltage			0.8	V
VI	Input voltage	0		VCC	V
ЮН	High-level output current			-24	mA
loL	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
fclock	Input clock frequency			60	MHz
TA	Operating free-air temperature	-40		85	°C



## **CDC208 DUAL 1-LINE TO 4-LINE CLOCK DRIVER** WITH 3-STATE OUTPUTS SCAS109F - APRIL 1990 - REVISED OCTOBER 1998

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST COMPLETONS	,,	T,	գ = 25°C	;	MINI	MAV	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
		4.5 V	4.4			4.4		
	I <sub>OH</sub> = -50 μA	5.5 V	5.4			5.4		
VOH	January 24 mA	4.5 V	3.94			3.8		V
	I <sub>OH</sub> = -24 mA	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	I 50 A	4.5 V			0.1		0.1	
	$I_{OL} = 50 \mu A$	5.5 V			0.1		0.1	
$\vee_{OL}$	Jan. 24 mA	4.5 V			0.36		0.44	V
	I <sub>OL</sub> = 24 mA	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ
Δl <sub>CC</sub> ‡	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			0.9		1	mA
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		4			·	pF
Co	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V		10		_		pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



<sup>&</sup>lt;sup>‡</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

## switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	T,	<b>Վ = 25°C</b>	;	MINI	BAAV	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>PLH</sub>	1A and 2A	Amy V	5.3	8.5	10.9	5.3	11.7	20
<sup>t</sup> PHL	TA and ZA	Any Y	3.6	7.7	11	3.6	11.5	ns
<sup>t</sup> PLH	1 <del>0E1</del> , 1 <del>0E2</del> , and	A.m., V	4.7	8.5	11.7	4.7	12.8	
<sup>t</sup> PHL	2 <del>0E1</del> , 2 <del>0E</del> 2	Any Y	4.4	8.4	11.3	4.4	12.4	ns
<sup>t</sup> PZH	1OE2 or 2OE2	A V	4.4	8.1	11.3	4.4	12.4	
t <sub>PZL</sub>	10E1 or 20E1	Any Y	5	9.6	13.3	5	14.9	ns
<sup>t</sup> PHZ	10E2 or 20E2	Any V	4.2	7.4	9.3	4.2	10.2	20
t <sub>PLZ</sub>	10E1 or 20E1	Any Y	5.4	7.5	9.2	5.4	9.9	ns

## switching characteristics, $V_{CC}$ = 5 V $\pm$ 0.25 V, $T_A$ = 25°C to 70°C (see Note 3 and Figures 1 and 2)

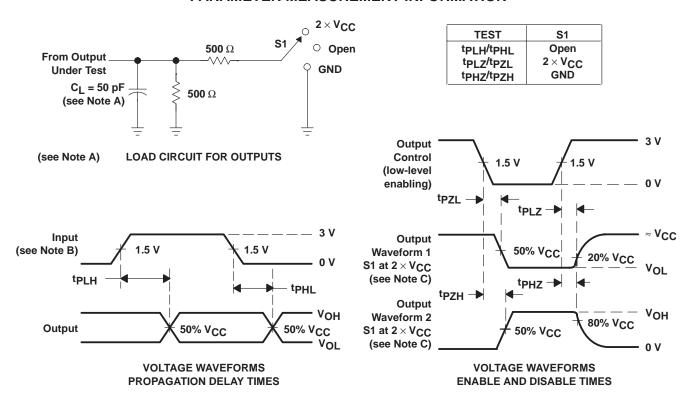
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
<sup>t</sup> PLH	4.4 and 0.4	Anna V	6.6	10.2	
t <sub>PHL</sub>	1A and 2A	Any Y	6.6	9.8	ns
t <sub>sk(o)</sub>	1A and 2A	Any Y		1	ns

NOTE 3: All specifications are valid only for all outputs switching simultaneously and in phase.

## operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT	
C <sub>pd</sub>	Dower dissination conscitance nor book	Outputs enabled	Cı = 50 pF. f = 1 MHz	96 pF	F
	Power dissipation capacitance per bank	Outputs disabled	$C_L = 50 \text{ pF},  f = 1 \text{ MHz}$	12	рг

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

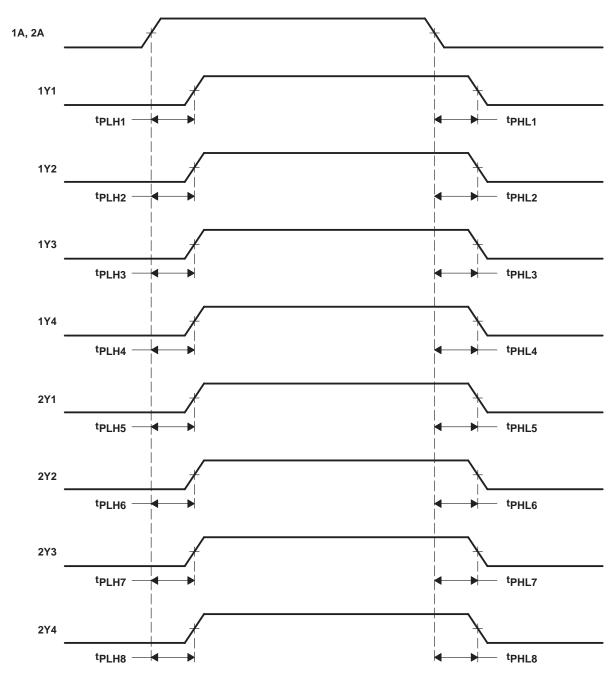
- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 3$  ns.  $t_f \leq 3$  ns. For testing pulse duration:  $t_r = t_f = 1$  to 3 ns. Pulse polarity can be either high-to-low-to-high or low-to-high-to-low.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

Figure 1. Load Circuit and Voltage Waveforms



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## PARAMETER MEASUREMENT INFORMATION



- NOTE A: Output skew,  $t_{Sk(0)}$ , is calculated as the greater of:

   The difference between the fastest and slowest of  $t_{PLHn}$  (n = 1, 2, ..., 8)

   The difference between the fastest and slowest of  $t_{PHLn}$  (n = 1, 2, ..., 8)

Figure 2. Waveforms for Calculation of  $t_{Sk(0)}$ 



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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CDC208DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		CDC208	Samples
CDC208DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		CDC208	Samples
CDC208NS	ACTIVE	SOP	NS	20	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC208	Samples
CDC208NSR	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC208	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE OPTION ADDENDUM

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## **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC208DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CDC208NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC208DWR	SOIC	DW	20	2000	367.0	367.0	45.0
CDC208NSR	SOP	NS	20	2000	367.0	367.0	45.0

## **PACKAGE MATERIALS INFORMATION**

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## **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CDC208DW	DW	SOIC	20	25	507	12.83	5080	6.6
CDC208NS	NS	SOP	20	40	530	10.5	4000	4.1

## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.





SOIC



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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